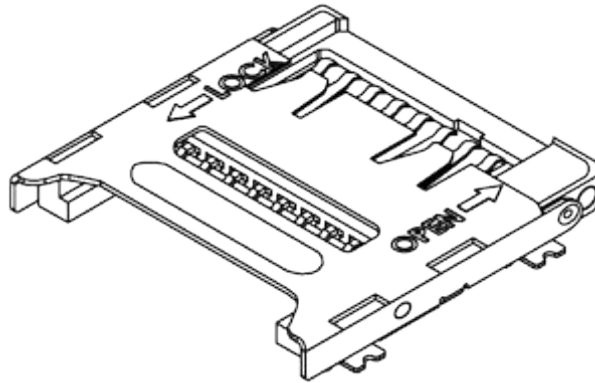


# PRODUCT SPECIFICATION

<b>Part Number</b>	MEM2065	<b>Rev</b>	A	<b>Date</b>	11/06/09		
<b>Product Description</b>	Micro SD Memory Card Connector, SMT, Hinged, 2.00mm Profile.				<b>Page</b>	1	
<b>Doc Number</b>	MEM2065	<b>Prepared</b>	<b>BW</b>	<b>Checked</b>	<b>PN</b>	<b>Approved</b>	<b>DR</b>



# GCT

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## 1.0 SCOPE.

This specification covers the Micro SD Memory Card Connector, SMT, MEM2065 series. (Hinged Type, SMT, 2.00mm profiles).

## 2.0 PRODUCT NAME AND PART NUMBER.

Micro SD Memory Card Connector, Hinged Type:MEM2065

## 3.0 PRODUCT SHAPE, DIMENSIONS AND MATERIAL.

Please refer to drawings.

## 4.0 RATINGS.

- 4.1 Current rating ..... 1.0A DC (per pin)
- 4.2 Voltage rating ..... 100 Volts AC(RMS)
- 4.3 Operating Temperature Range ..... -25°C TO +85°C
- 4.4 Storage Temperature ..... -35°C TO +60°C

## 5.0 TEST AND MEASUREMENT CONDITIONS.

Product is designed to meet electrical, mechanical and environmental performance requirements specified in Paragraph 6.0. All tests are performed in ambient conditions unless otherwise specified.

## 6.0 PERFORMANCE.

Item	Test Condition	Requirement
Examination of Product	Visual, dimensional and functional inspection as per quality plan.	Product shall meet requirements of product drawing and specification.

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## 6.1 Electrical Performance.

Item	Test Condition	Requirement
Contact Resistance	Measure and record contact resistance of mated connector using test current of 10mA max and 20 mV open circuit voltage in accordance with MIL-STD-202.	Less than 100 mΩ at end of test
Insulation Resistance	Apply 500Volts DC between adjacent contacts of mated connectors for one minute in accordance with MIL-STD-202, Method 302, and Condition B.	Greater than 500 MΩ
Dielectric Strength	Mate connectors and apply 500 V AC for 1 minute between adjacent terminal ground, in accordance with MIL-STD-202 method 301.	No creeping discharge or flash over. Current leakage less than 1 mA

## 6.2 Mechanical Performance.

Item	Test Condition	Requirement
Contact force	Apply axial pull out force on the connector assembled in the housing at a speed: 25 ± 3 mm/minute.	0.98 N / pin Min
Durability	The connector should be mated and unmated for 5000 cycles with 0.6mm travel.	No evidence of physical damage.  Contact Resistance ≤ 100mΩ at end of test.
Vibration	Subject mated connectors to 10 to 55 to 10 Hz frequency span over 1 minute at a 1.5mm amplitude. Test to be conducted on 3 mutually perpendicular planes for 2hrs each with 10mA applied and in accordance with MIL-STD-202 Method 201.	No electrical discontinuity greater than 1 μ sec. shall occur. No damage to product.  Contact Resistance ≤ 100mΩ at end of test.
Mechanical Shock	Subject the part to a 490 m/s <sup>2</sup> half sine wave acceleration for 11 ms. Three shocks to be applied in each of the X, Y and Z planes and in both directions. A total of 18 shocks and in accordance with MIL-STD-202 Method 213	No electrical discontinuity greater than 1 μ sec. shall occur. No damage to product. Contact Resistance ≤ 100mΩ at end of test .

# PRODUCT SPECIFICATION

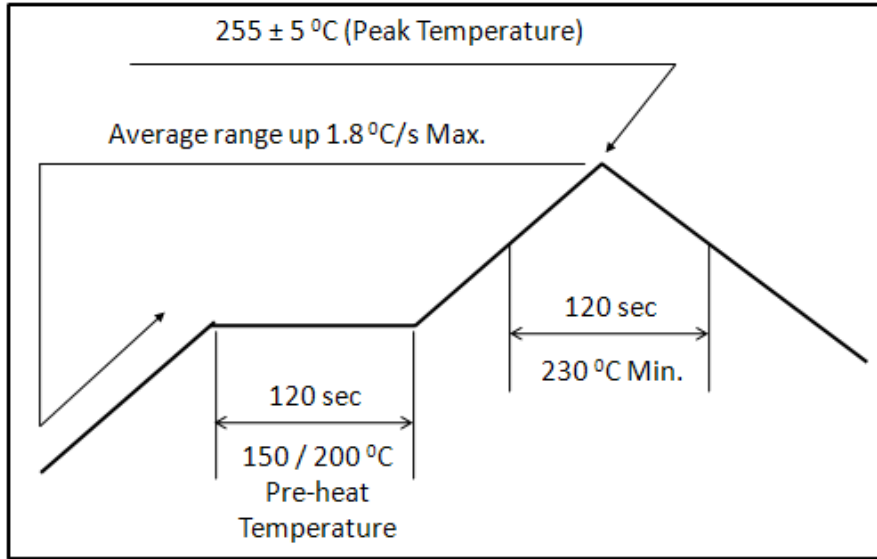
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## 6.3 Environmental Performance and Others.

Item	Test Condition	Requirement
Thermal Shock	Mate Connector and perform the following thermal cycle :-  -55+/-3°C for 30 minutes. . +85+/-2°C for 30 minutes.  Repeat for 5 cycles in accordance with MIL-STD-202, Method 107D, condition A.	No evidence of physical damage, discharge, flashes or corrosion in contact areas.  Contact Resistance Less than 100mΩ at end of test.  Insulation Resistance greater than 500MΩ at end of test.
Humidity Test	Mate connector and expose to temperature of 40±2°C with 95% RH for 96 hours then place in ambient temperature for 1 to 2 hrs. In accordance with MIL-STD-202, Method 103.	
Salt Water Spray	Subject mated connectors to 35±2°C and 5±1% salt condition for 48 hours. Test in accordance with MIL-STD-202, Method 101 Condition B.	
Temperature Life (High)	Subject product to 85±2°C for 96 hours continuously in accordance with MIL-STD-202, Method 108.	
Temperature Life (Cold)	Subject product to -40±2°C for 96 hours continuously in accordance with MIL-STD-202, Method 108.	
Solderability	Dip solders tails into molten solder, held at a temperature of 230±5°C for 3±0.5 seconds, in accordance with MIL-STD-202F.	
Resistance to Reflow Soldering Heat.	Mount connector, place in reflow oven and expose to the temperature profile shown in fig 1.0.	
Temperature rise	Apply rated current load of 0.3A per contact in accordance with UL498.	30°C Max temperature rise.

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**Fig.1. Recommended Reflow Temp. Profile**

## 7.0 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test Group	Sample Groups									
Test Description	A	B	C	D	E	F	G	H	I	J
Examination of Products	1,5	1	1	1,5	1,5	1,5	1,5	1,5	1,5	1,5
Contact Resistance	2			2,4	2,4	2,4	2,4	2,4	2,4	2,4
Insulation Resistance	3									
Dielectric Withstanding Voltage	4									
Contact Force			2							
Durability				3						
Vibration					3					
Mechanical Shock						3				
Thermal Shock									3	
Humidity								3		
Salt Spray										3
Heat Temperature						3				
Cold Temperature							3			
Temperature Rise				3						

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